

L1 20 "KHANDROS, IGOR Y"/IN
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1. 5,489,749, Feb. 6, 1996, Semiconductor connection components and method with releasable lead support; Thomas H. DiStefano, et al., 174/261; 29/832, 835; 174/260, 262; 361/760, 774, 783; 439/78, 84 [IMAGE AVAILABLE]

2. 5,476,211, Dec. 19, 1995, Method of manufacturing electrical contacts, using a sacrificial member; **Igor Y. Khandros**, 228/180.5; 29/840, 843; 228/199; 427/117 [IMAGE AVAILABLE]

3. 5,390,844, Feb. 21, 1995, Semiconductor inner lead bonding tool; Thomas H. DiStefano, et al., 228/180.21, 49.5, 212 [IMAGE AVAILABLE]

4. 5,367,764, Nov. 29, 1994, Method of making a multi-layer circuit assembly; Thomas H. DiStefano, et al., 29/830, 852; 174/260, 262; 216/20; 439/69 [IMAGE AVAILABLE]

✓ 5. 5,347,159, Sep. 13, 1994, Semiconductor chip assemblies with face-up mounting and rear-surface connection to substrate; **Igor Y. Khandros**, et al., 257/692, 696 [IMAGE AVAILABLE]

6. 5,346,861, Sep. 13, 1994, Semiconductor chip assemblies and methods of making same; **Igor Y. Khandros**, et al., 437/209, 211, 215, 217, 220 [IMAGE AVAILABLE]

7. 5,282,312, Feb. 1, 1994, Multi-layer circuit construction methods with customization features; Thomas H. DiStefano, et al., 29/830, 846, 852; 427/97 [IMAGE AVAILABLE]

✓ 8. 5,258,330, Nov. 2, 1993, Semiconductor chip assemblies with fan-in leads; **Igor Y. Khandros**, et al., 437/209, 211, 215, 217 [IMAGE AVAILABLE]

9. 5,198,189, Mar. 30, 1993, Liquid metal matrix thermal paste; Richard B. Booth, et al., 420/555; 252/387 [IMAGE AVAILABLE]

10. 5,192,618, Mar. 9, 1993, Corrosion protection by FeMn by ion implantation; Gerald S. Frankel, et al., 428/457; 148/101, 222, 239; 204/157.4, 157.44, 157.46, 157.47, 157.5; 360/110, 113; 427/130; 428/469, 611, 632, 677, 681, 694R, 920, 928 [IMAGE AVAILABLE]

11. 5,173,256, Dec. 22, 1992, Liquid metal matrix thermal paste; Richard B. Booth, et al., 420/590 [IMAGE AVAILABLE]

✓ 12. 5,148,266, Sep. 15, 1992, Semiconductor chip assemblies having interposer and flexible lead; **Igor Y. Khandros**, et al., 257/773, 668, 669 [IMAGE AVAILABLE]

✓ 13. 5,148,265, Sep. 15, 1992, Semiconductor chip assemblies with fan-in leads; **Igor Y. Khandros**, et al., 257/773, 668, 669 [IMAGE AVAILABLE]

14. 5,134,038, Jul. 28, 1992, Thin film magnetic recording medium with controlled grain morphology and topology; Robert J. Baseman, et al., 428/611; 360/134, 135, 136; 428/336, 612, 614, 621, 642, 660, 661, 693, 694BR, 694SG, 694TS, 900, 928, 939 [IMAGE AVAILABLE]

15. 5,086,558, Feb. 11, 1992, Direct attachment of semiconductor chips to a substrate with a substrate with a thermoplastic interposer; Gary W. Grube, et al., 29/832, 840, 841 [IMAGE AVAILABLE]

16. 5,062,896, Nov. 5, 1991, Solder/polymer composite paste and method; Wu-Song Huang, et al., 106/287.19; 148/24; 252/512, 514 [IMAGE AVAILABLE]

17. 4,536,232, Aug. 20, 1985, Erosion and corrosion resistant cast iron alloy containing chromium, nickel and molybdenum; **Igor Y. Khandros**, et al., 148/542, 324, 335, 616 [IMAGE AVAILABLE]

18. 4,424,853, Jan. 10, 1984, Foundry practices; **Igor Y. Khandros**, et al., 164/57.1, 66.1 [IMAGE AVAILABLE]

19. 4,377,196, Mar. 22, 1983, Method of centrifugally casting a metal tube; **Igor Y. Khandros**, 164/66.1, 95, 96, 114 [IMAGE AVAILABLE]

20. 4,357,394, Nov. 2, 1982, Centrifugal casting; **Igor Y. Khandros**, 428/595, 610, 652, 653 [IMAGE AVAILABLE]

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1. 5,414,298, May 9, 1995, Semiconductor chip assemblies and components with pressure contact; Gary Grube, et al., 257/690, 692, 701 [IMAGE AVAILABLE]

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